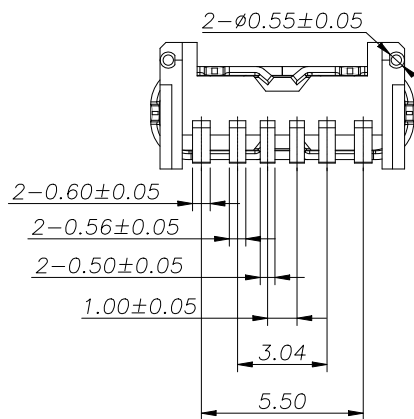
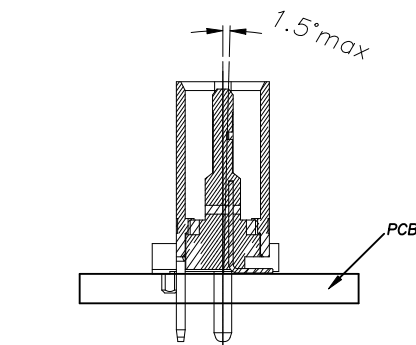
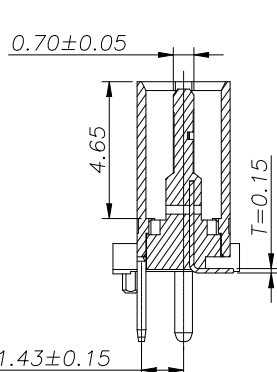
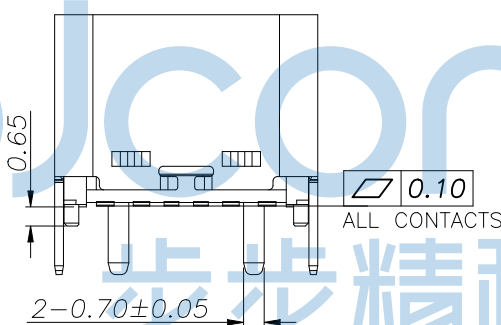
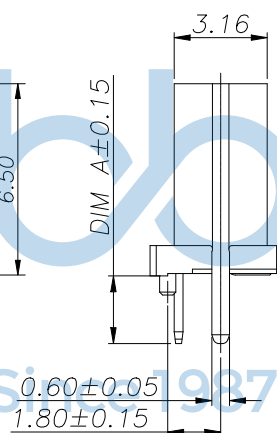
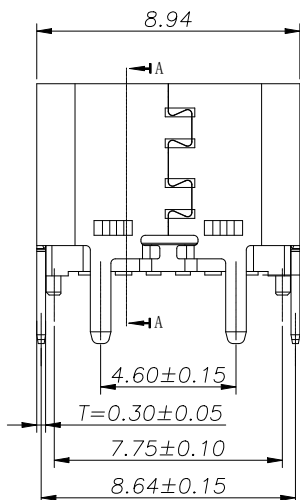
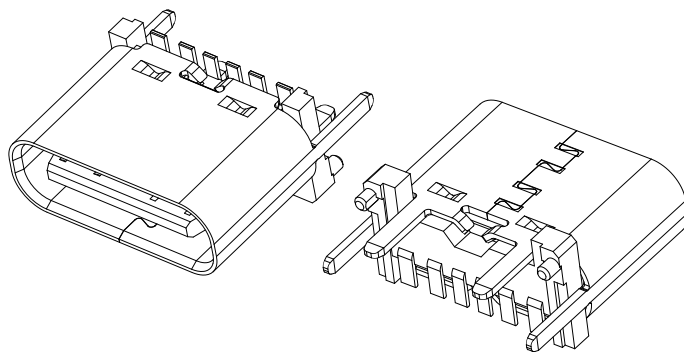
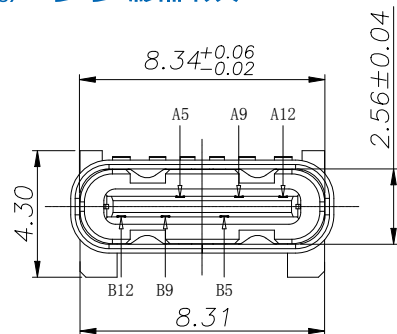


| REV. | ECN NO | CONTENT | DATE | ENGINEER |
|------|--------|-----------------|------|----------|
| A0 | | Initial release | / | TSP |



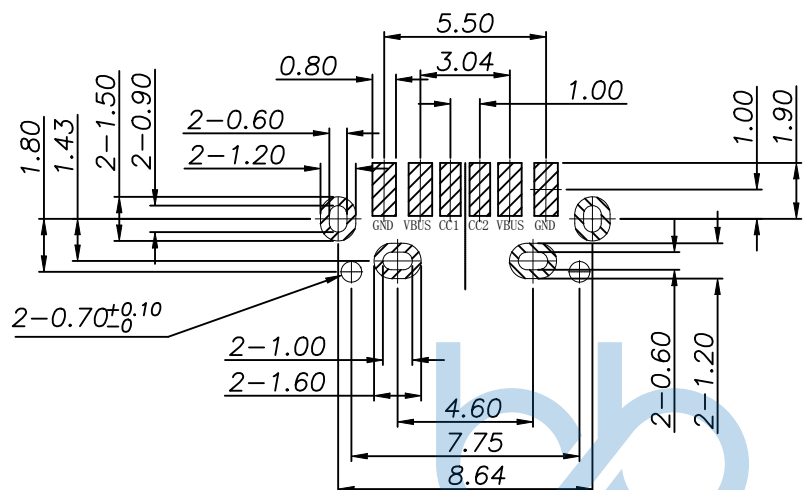
NOTE:
1.MATERIAL SPECIFICATION:
1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,PA9T BLACK UL94 V-0.
2.TERMINAL: COPPER ALLOY C18150
3.MID PLATE: STAINLESS STEEL SUS304
4.FRONT SHELL: STAINLESS STEEL SUS304
2.PLATING SPECIFICATION:
2-1.TERMINAL:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au 3u" PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW Au 1u"
2-2.FRONT SHELL:
PLATING SPECIFICATIONS FOLLOW Ni
2-3.MID PLATE
CLEAR ONLY
3.MECHANICAL PERFORMANCE,
3-1.INSERTION FORCE: 0.5~2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3-3.DURABILITY: 10000 CYCLES.
4.ELECTRICAL PERFORMANCE,
4-1. VOLTAGE RATING:20 V DC/AC (RMS. max)
CURRENT RATING:3AMPS MIN
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mA.
4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.
6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.



DIM *A* = 0.70
DIM *A* = 1.70
DIM *A* = 2.30

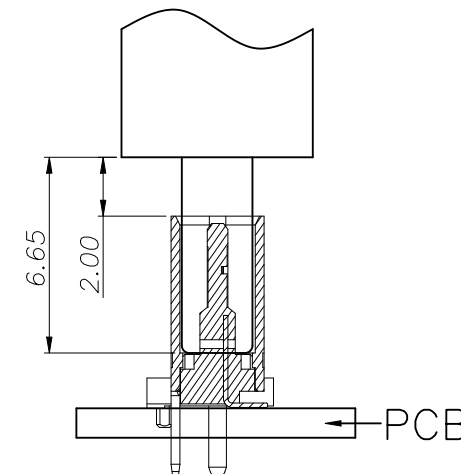
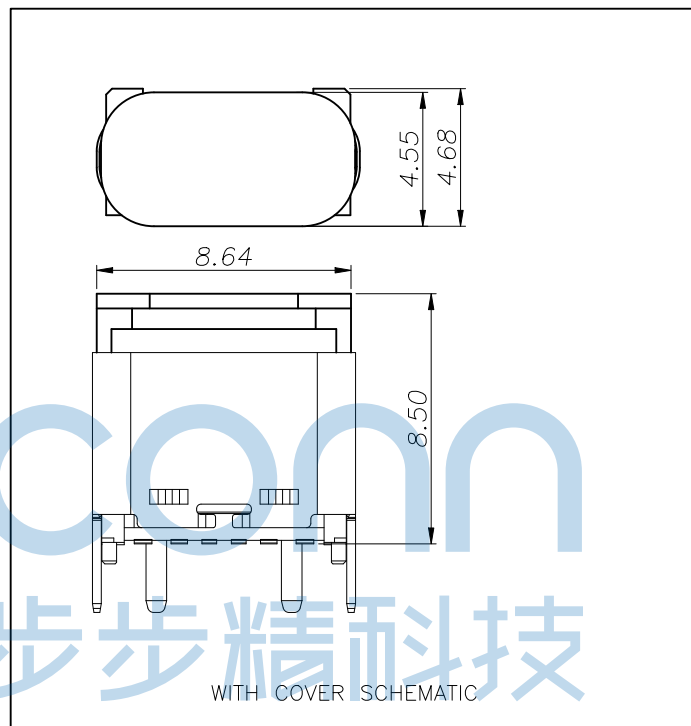
| | | | |
|--|---------|---|--|
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| PDWG.NO: 0049-1 | DR. TSP | NAME:TYPE-C 6P 母座 直立式 四脚插 带柱 脚长0.70 端子SMT 端子镀金3u H=6.50 编带 | PJ. NO.: 126-224-060001-M8G SIZE: A4 DRW NO.: |
| | | FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3 | |

| | | | | |
|------|--------|-----------------|------|----------|
| REV. | ECN NO | CONTENT | DATE | ENGINEER |
| A0 | | Initial release | / | TSP |



RECOMMENDED PCB LAYOUT

THICKNESS ;DEFAULT TOLERANCE:±0.05



Since 1987



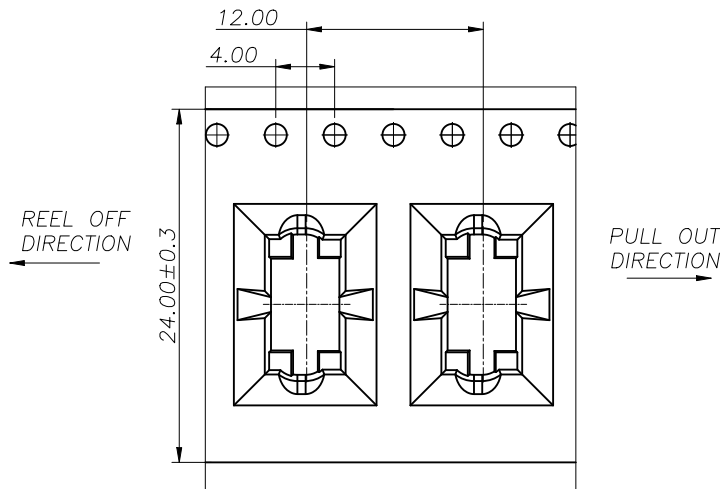
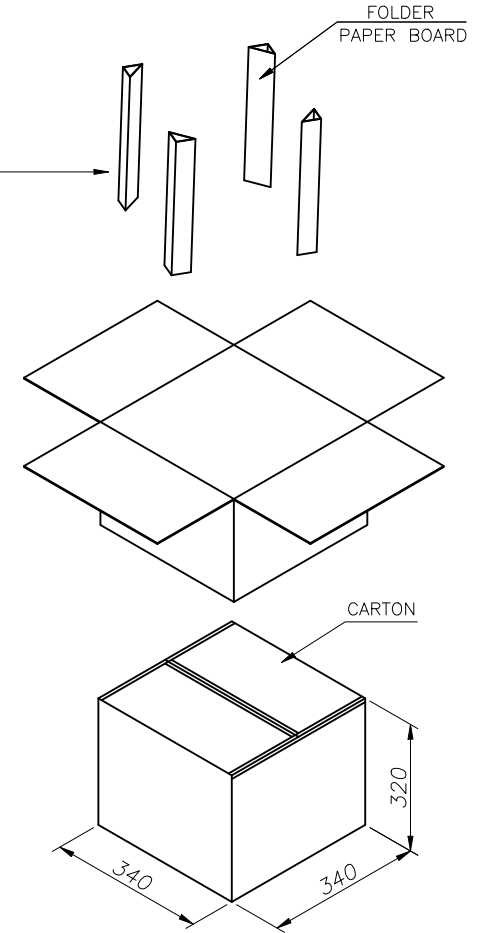
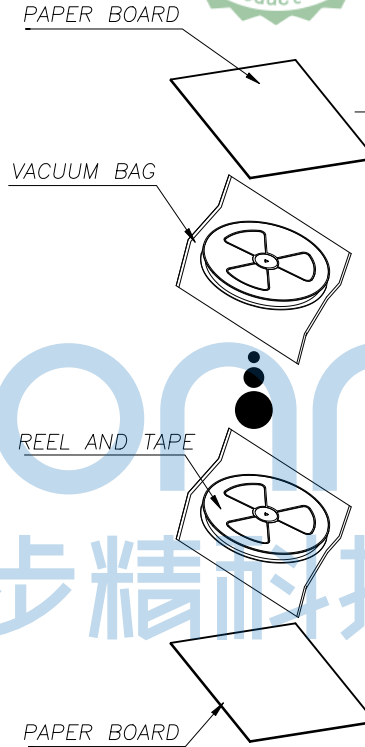
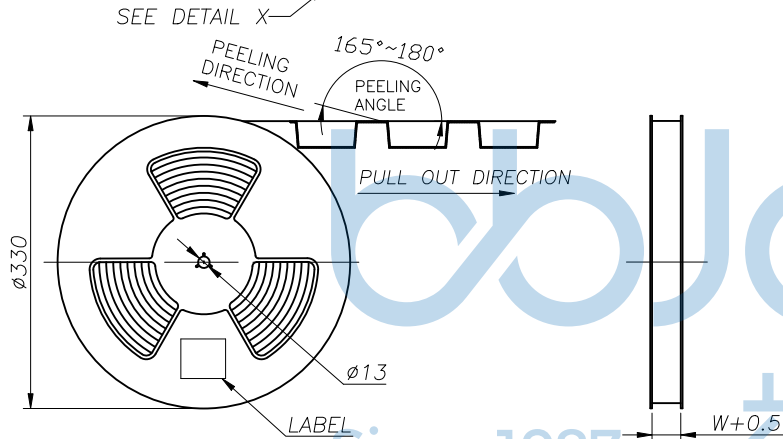
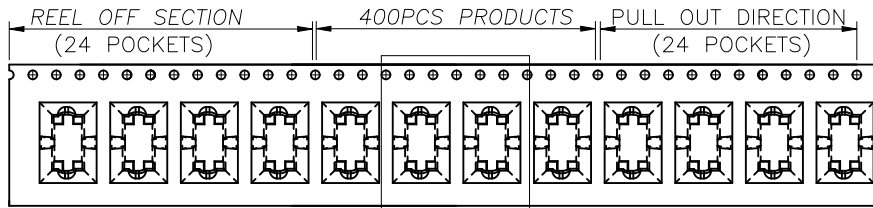
PIN ASSIGNMENTS

| | | | |
|-----|-------------|-----|-------------|
| A5 | CC1 | B12 | GND |
| A9 | VBUS | B9 | VBUS |
| A12 | GND | B5 | CC2 |
| PIN | SIGNAL NAME | PIN | SIGNAL NAME |

| | | | | | |
|--|----------|--|-----|--|-----------------------------|
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| APPD. | JM_Zheng | PJ. NO.: 126-224-060001-M8G | | SIZE: A4 DRW NO.: | |
| CHKD. | LYX | FINISH: SEE NOTES | | MAT'L.: SEE NOTES | |
| PDWG.NO: | 0049-1 | DR. | TSP | SCALE: N/A | REV.: A0 UNIT: mm PAGE: 2/3 |



| REV. | ECN NO | CONTENT | DATE | ENGINEER |
|------|--------|-----------------|------|----------|
| A0 | | Initial release | / | TSP |



| | REEL/TRAY | CARTON |
|-----------------|-----------|--------|
| CONNECTOR (PCS) | 400 | 4000 |

| | | | |
|--|----------------|--|--|
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| PDWG.NO: 0049-1 | DR. TSP | .X: ± 0.38 .XX: ± 0.25 .XXX: ± 0.13 X': $\pm 3'$.X': $\pm 2'$.XX': $\pm 1'$ | NAME: TYPE-C 6P 母座 直立式 四脚插 带柱 脚长0.70 端子SMT 端子镀金3u H=6.50 编带 |
| | APPD. JM_Zheng | PJ. NO.: 126-224-060001-M8G | SIZE: A4 DRW NO.: |
| | CHKD. LYX | FINISH: SEE NOTES | MAT'L.: SEE NOTES |
| | | SCALE: N/A | REV.: A0 UNIT: mm PAGE: 3/3 |